GeneSiC
S E M I C O N D U C T O R

GAP3SLT33-214

Silicon Carbide Power Schottky Diode

| V_{RRM}	=	3300 V
V_F	=	1.7 V
I_F	=	0.3 A
Q_C	=	52 nC

Features

- 3300 V Schottky rectifier
- 175 °C maximum operating temperature
- Electrically isolated base-plate
- Positive temperature coefficient of V_F
- Fast switching speeds
- Superior figure of merit Q_C/I_F

Package

- RoHS Compliant

PIN 1

PIN 2

SMB / DO – 214AA

Advantages

- Improved circuit efficiency (Lower overall cost)
- Significantly reduced switching losses compare to Si PiN diodes
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Low reverse recovery current
- Low device capacitance
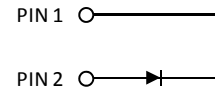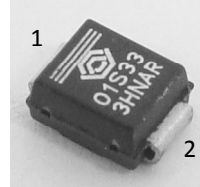
Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- High Voltage Multipliers
- Military Power Supplies

Maximum Ratings at T_j = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		3300	V
Continuous forward current	I_F	$T_C \leq 125$ °C	0.3	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 125$ °C	0.35	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25$ °C, $t_P = 10$ ms	tbd	A
		$T_C = 125$ °C, $t_P = 10$ ms	tbd	
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25$ °C, $t_P = 10$ μs	tbd	A
I^2t value	$\int i^2\, dt$	$T_C = 25$ °C, $t_P = 10$ ms	tbd	A^2S
Power dissipation	P_{tot}	$T_C = 25$ °C	25	W
Operating and storage temperature	T_j , T_{stg}		-55 to 175	°C

Electrical Characteristics at T_j = 175 °C, unless otherwise specified

Parameter	Symbol	Conditions		Values			Unit
				min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 0.3$ A, $T_j = 25$ °C			1.7		V
		$I_F = 0.3$ A, $T_j = 175$ °C			3.9		
Reverse current	I_R	$V_R = 3300$ V, $T_j = 25$ °C			1.3	5	μA
		$V_R = 3300$ V, $T_j = 175$ °C			14	20	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $dI_F/dt = 35$ A/μs $T_j = 175$ °C	$V_R = 1500$ V		52		nC
Switching time	t_s		$V_R = 1500$ V		< 60		ns
Total capacitance	C	$V_R = 1$ V, f = 1 MHz, $T_j = 25$ °C			42		pF
		$V_R = 400$ V, f = 1 MHz, $T_j = 25$ °C			8		
		$V_R = 1000$ V, f = 1 MHz, $T_j = 25$ °C			7		

Thermal Characteristics

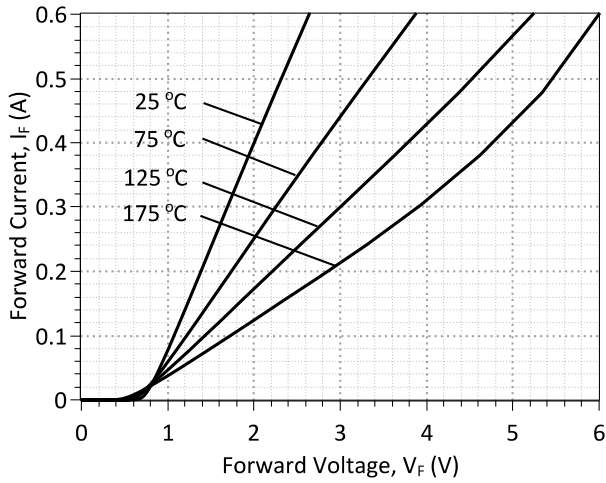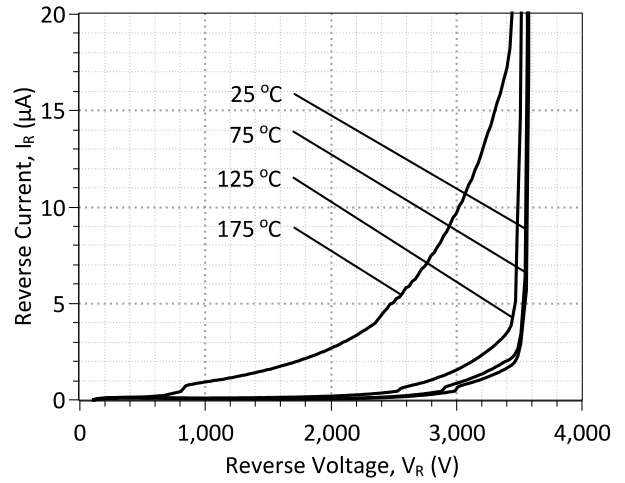| Parameter	Symbol		Conditions		Value	Unit
Thermal resistance, junction – Cu lead frame	R_{thJC}				1.42	°C/W

Figure 1: Typical Forward Characteristics

Figure 2: Typical Reverse Characteristics
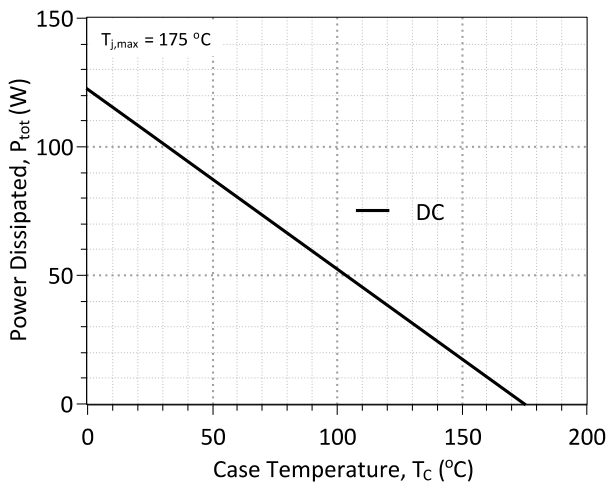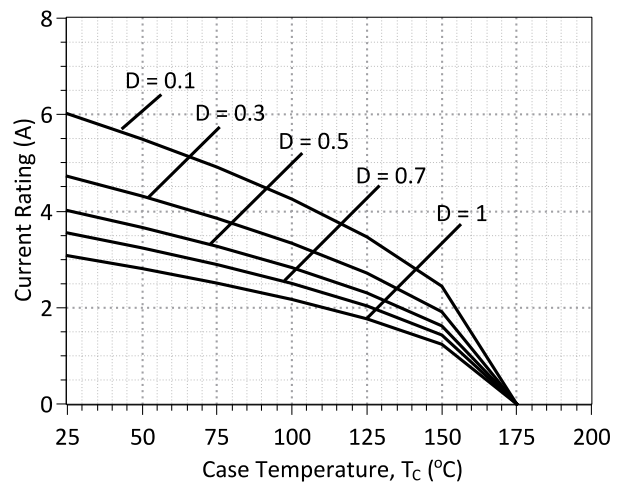

Figure 3: Power Derating Curve

Figure 4: Current Derating Curves (D = t_p/T, t_p = 400 μs) (Considering worst case Zth conditions)
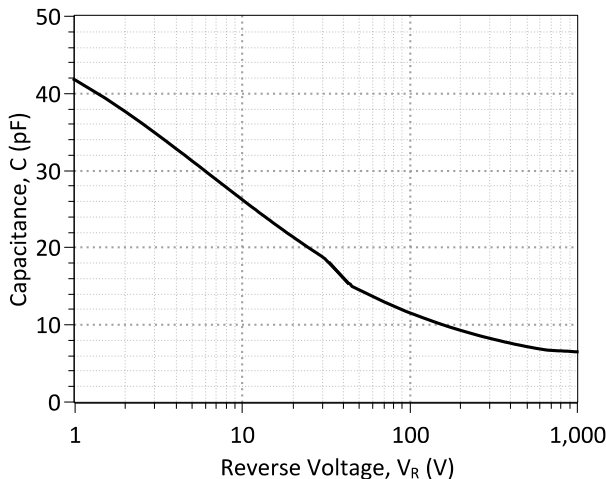

Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

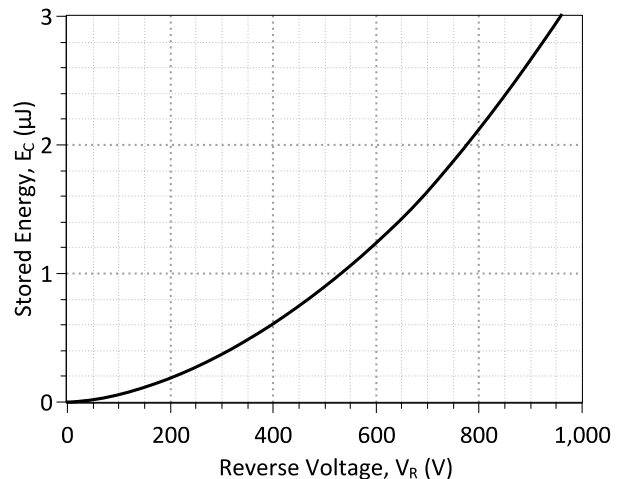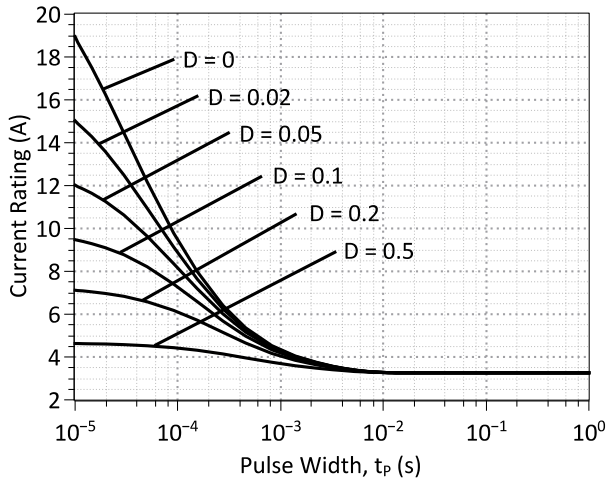Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics

Figure 7: Current vs Pulse Duration Curves at T_C = 150 °C

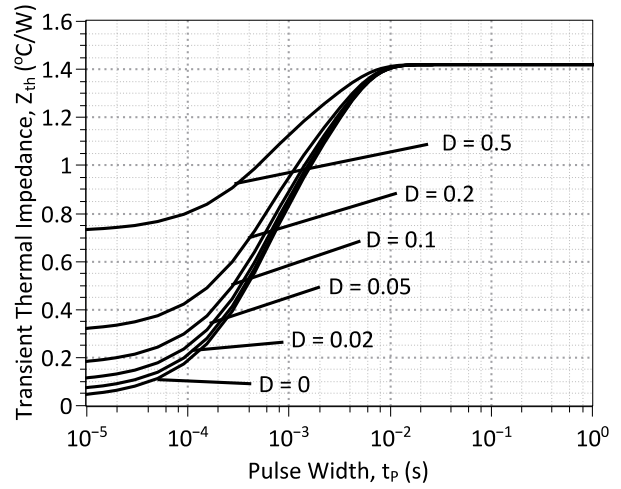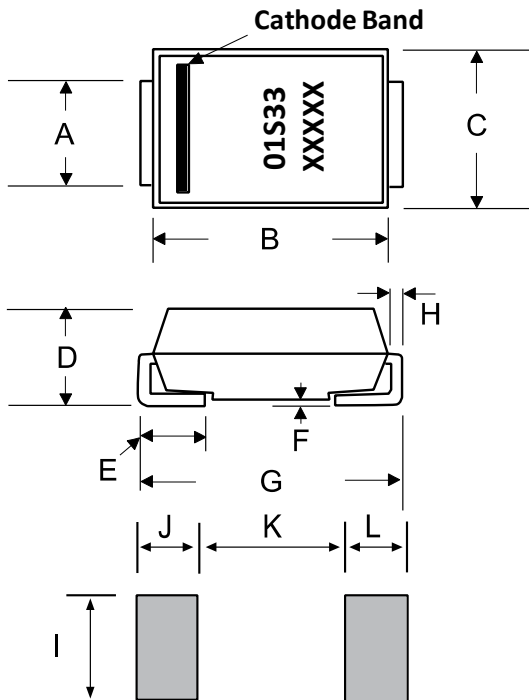Figure 8: Transient Thermal Impedance

Package Dimensions:

SMB / DO-214AA   PACKAGE OUTLINE

Cathode Band

01S33
XXXXX

Dimensions	Inches		Millimeters	
	Min	Max	Min	Max
A	0.077	0.086	1.950	2.200
B	0.160	0.180	4.060	4.570
C	0.130	0.155	3.300	3.940
D	0.084	0.096	2.130	2.440
E	0.030	0.060	0.760	1.520
F	-	0.008	-	0.203
G	0.205	0.220	5.210	5.590
H	0.006	0.012	0.152	0.305
I	0.089	-	2.260	-
J	0.085	-	2.160	-
K	-	0.107	-	2.740
L	0.085	-	2.160	-

NOTE
1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS
3. CONTROLLED LEAD COPLANARITY <D> 0.004 INCH MAXIMUM

Revision History

Date	Revision	Comments	Supersedes
2013/09/09	0	Initial Release	

Published by

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the GAP3SLT33-214 device.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0              $
*      $Date:    09-SEP-2013         $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*      http://www.genesicsemi.com/index.php/sic-products/schottky
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
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*
* These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
* OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
* TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
* PARTICULAR PURPOSE."
* Models accurate up to 2 times rated drain current.
*
* Start of GAP3SLT33-214 SPICE Model
*
.SUBCKT GAP3SLT33 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0535); Temperature Dependant Resistor
D1 INT KATHODE GAP3SLT33_25C; Call the 25C Diode Model
D2 ANODE KATHODE GAP3SLT33_PIN; Call the PiN Diode Model
.MODEL GAP3SLT33_25C D
+ IS      1.39E-14      RS        2.88
+ N       1.0120127     IKF       36.05007504
+ EG      1.2           XTI       -3
+ CJO     6.01E-11      VJ        0.924257443
+ M       0.3084545     FC        0.5
+ TT      1.00E-10      BV        3700
+ IBV     1.00E-03      VPK       3300
+ IAVE    3.00E-01      TYPE      SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL GAP3SLT33_PIN D
+ IS      178.99E-18    RS        15
+ N       5             EG        3.23
+ XTI     50            FC        0.5
+ TT      0             BV        3700
+ IBV     1.00E-03      VPK       3300
+ IAVE    3.00E-01      TYPE      SiC_PiN
.ENDS
* End of GAP3SLT33-214 SPICE Model
```